Features

- ESD Protected Up To 2KV (HBM)
- High Dense Cell Design For Extremely Low RDS(ON)
- Moisture Sensitivity Level 1
- Halogen Free. “Green” Device(Note1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

N-CHANNEL MOSFET

Maximum Ratings

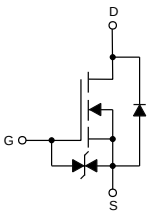
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 305°C/W Junction to Ambient(Note2)

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DS}	50	V
Gate-Source Volltage		V_{GS}	±20	V
Continuous Drain Current	T_A=25°C	I_D	0.37	A
	T_A=70°C		0.3	
Pulsed Drain Current(Note 3)		I_{DM}	1.48	A
Total Power Dissipation (Note 4)		P_D	0.4	W

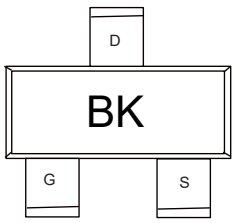
Note:

1. Halogen free "Green” products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. P_D is based on max. junction temperature, using junction-ambient thermal resistance.

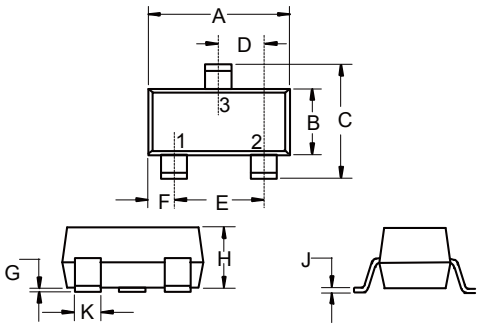
Internal Structure and Marking Code



1. GATE
2. SOURCE
3. DRAIN

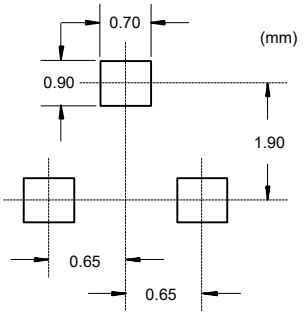


SOT-323



DIMENSIONS					
DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.071	0.087	1.80	2.20	
B	0.045	0.053	1.15	1.35	
C	0.083	0.096	2.10	2.45	
D	0.026		0.65		TYP.
E	0.047	0.055	1.20	1.40	
F	0.012	0.016	0.30	0.40	
G	0.000	0.004	0.00	0.10	
H	0.035	0.044	0.90	1.10	
J	0.002	0.010	0.05	0.25	
K	0.006	0.016	0.15	0.40	

Suggested Solder Pad Layout



ELECTRICAL CHARACTERISTICS (Ta=25℃ unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS}=0V, I_D=250μA	50			V
Gate-Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=250μA	0.5	1.0	1.5	V
Gate-Body Leakage Current	I_{GSS}	V_{GS}=±20V, V_{DS}=0V			±10	μA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=50V, V_{GS}=0V			1	μA
Drain-Source On-Resistance	$R_{DS(on)}$	V_{GS}=10V, I_D=0.5A		1	1.5	Ω
		V_{GS}=4.5V, I_D=0.2A		1.2	2.3	
		V_{GS}=2.5V, I_D=0.1A		1.7	4.1	
Forward Transconductance	g_{FS}	V_{DS}=10V, I_D=0.2A		370		mS
Gate Resistance	R_g	f=1 MHz, Open drain		90		Ω
Diode Characteristics						
Continuous Body Diode Current	I_S				0.37	A
Diode Forward Voltage	V_{SD}	V_{GS}=0V, I_S=0.3A			1.4	V
Reverse Recovery Time	t_{rr}	I_F=0.3A, dI_F/dt=100A/μs		11		ns
Reverse Recovery Charge	Q_{rr}			3		nC
Dynamic Characteristics						
Input Capacitance	C_{iss}	V_{DS}=30V,V_{GS}=0V,f=1MHz		30		pF
Output Capacitance	C_{oss}			6		
Reverse Transfer Capacitance	C_{rss}			3.8		
Total Gate Charge	Q_g	V_{DS}=30V,V_{GS}=10V,I_D=0.3A		1.17		nC
Gate-Source Charge	Q_{gs}			0.14		
Gate-Drain Charge	Q_{gd}			0.25		
Turn-On Delay Time	$t_{d(on)}$	V_{DD}=30V,V_{GS}=10V, R_G=3.9Ω, I_D=0.3A		2		ns
Turn-On Rise Time	t_r			3		
Turn-Off Delay Time	$t_{d(off)}$			8		
Turn-Off Fall Time	t_f			11		

Curve Characteristics

Fig.1 - Typical Output Characteristics

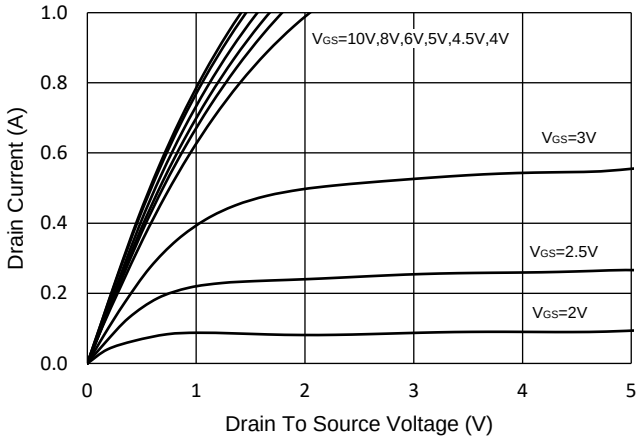


Fig.2 - Transfer Characteristic

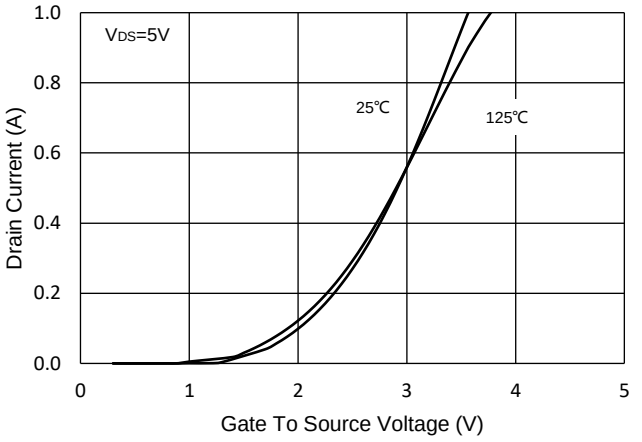


Fig.3 - $R_{DS(ON)}$ - V_{GS}

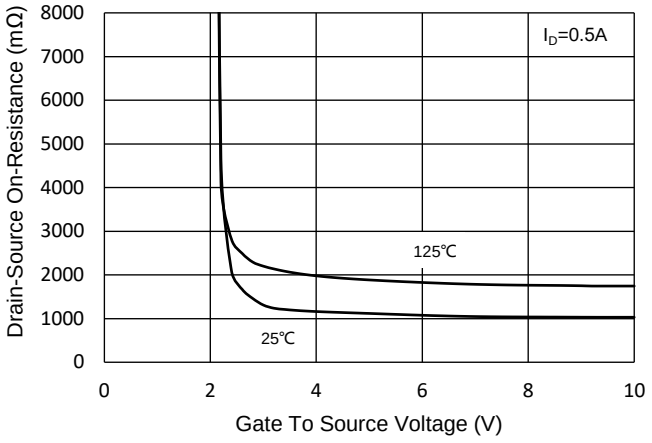


Fig.4 - $R_{DS(ON)}$ - I_D

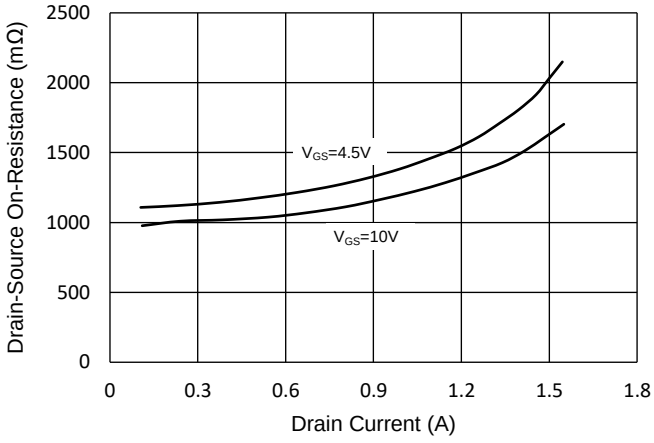


Fig.5 - Capacitance Characteristics

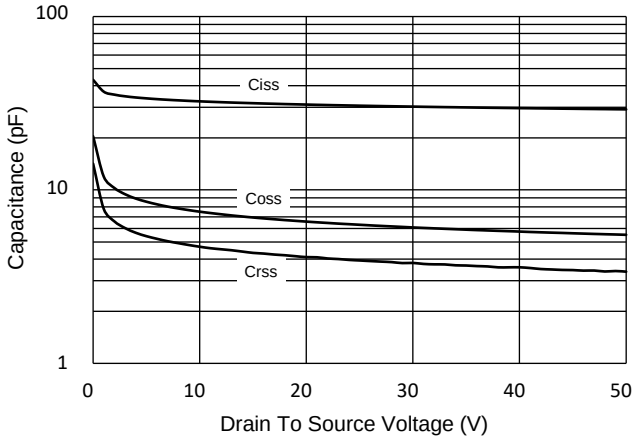
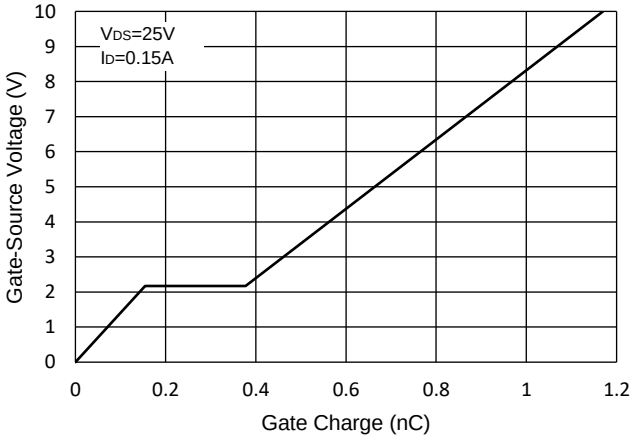


Fig.6 - Gate Charge



Curve Characteristics

Fig.7 - Normalized Threshold Voltage

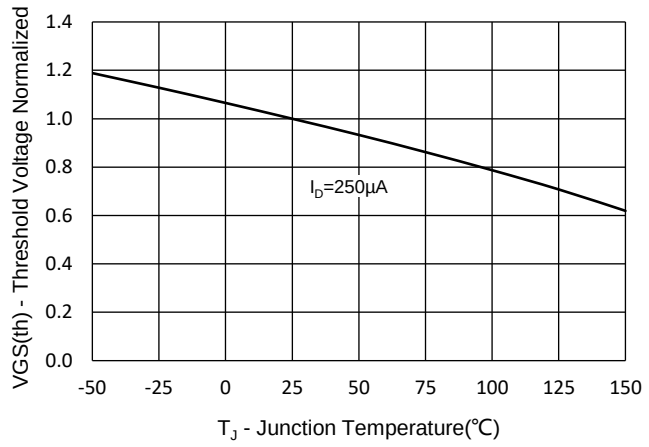


Fig.8 - Normalized On Resistance Characteristics

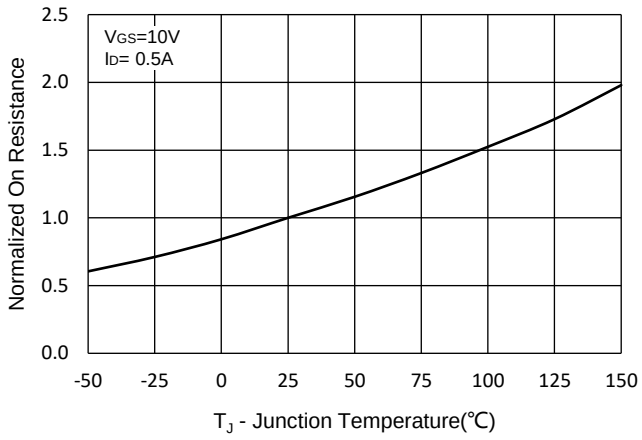


Fig.9 - I_S - V_{SD}

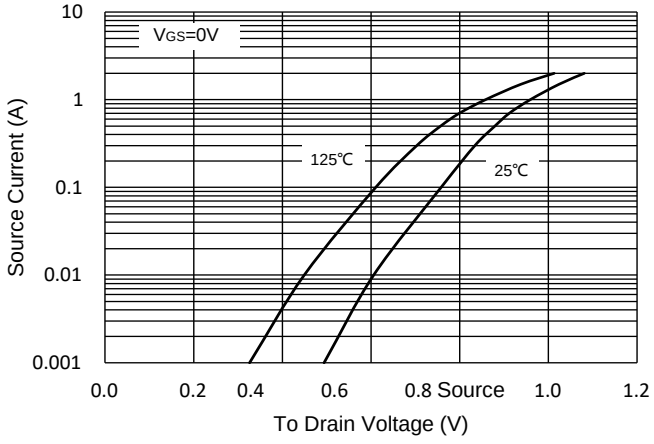


Fig.10 - Drain Current

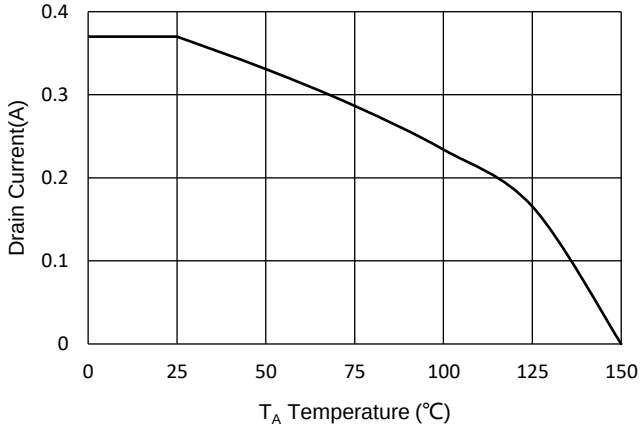
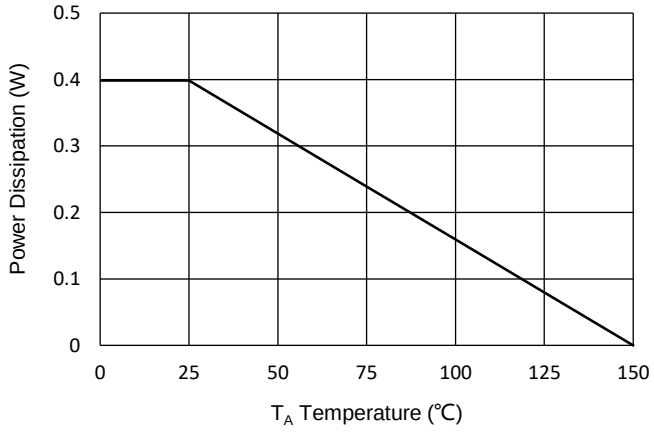


Fig.11 - PD Dissipation



Curve Characteristics

Fig.12 - Safe Operation Area

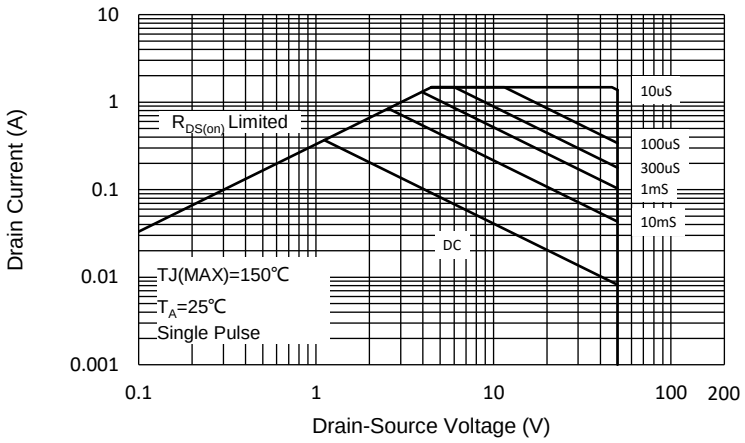
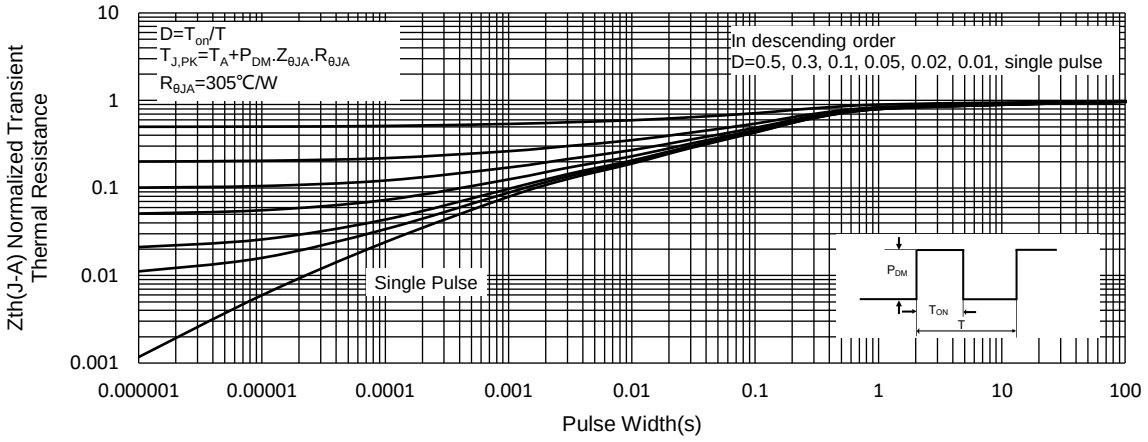


Fig.13 - Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 3Kpcs/Reel

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